

1/33

FIG. 1

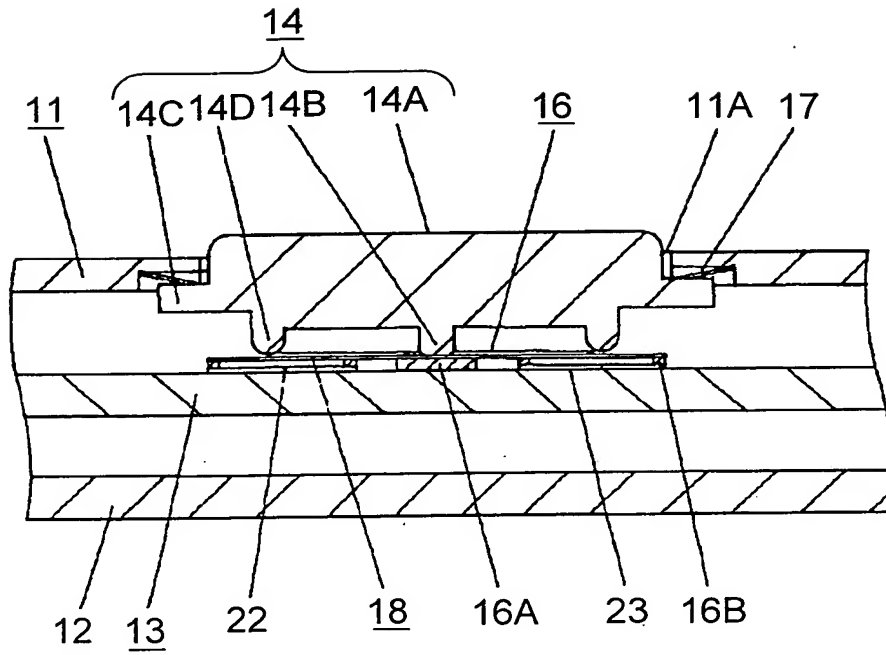
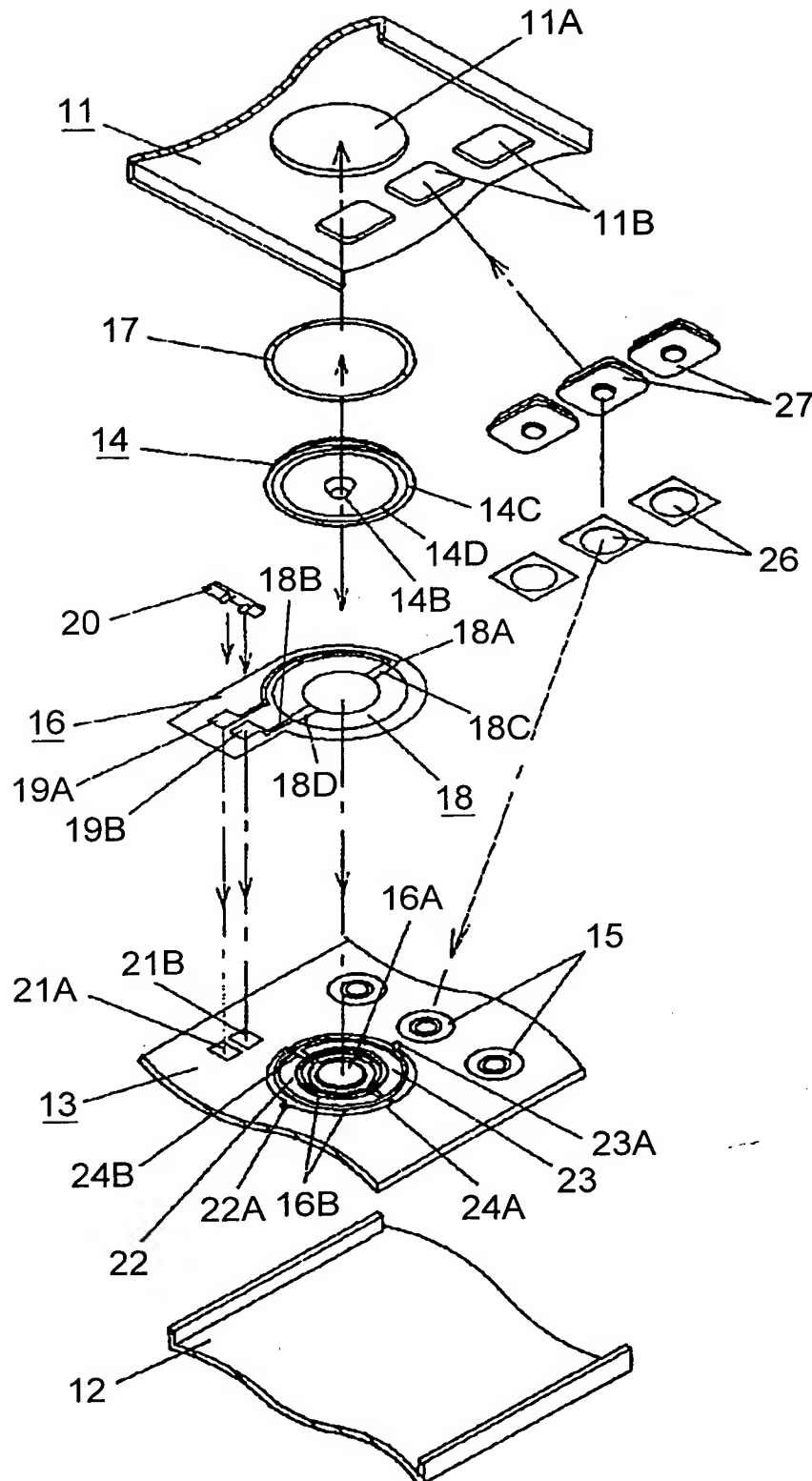


FIG. 2



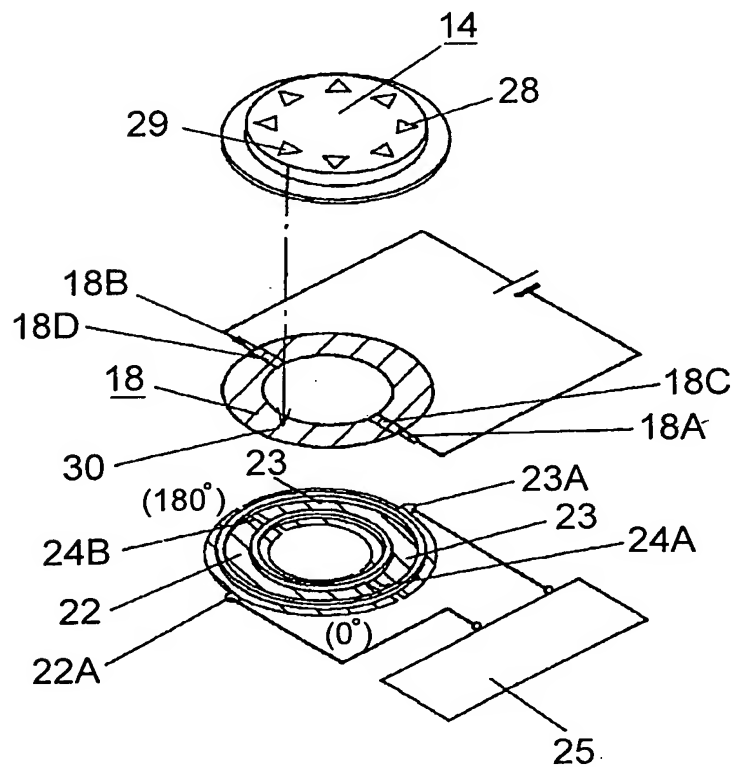


FIG. 5

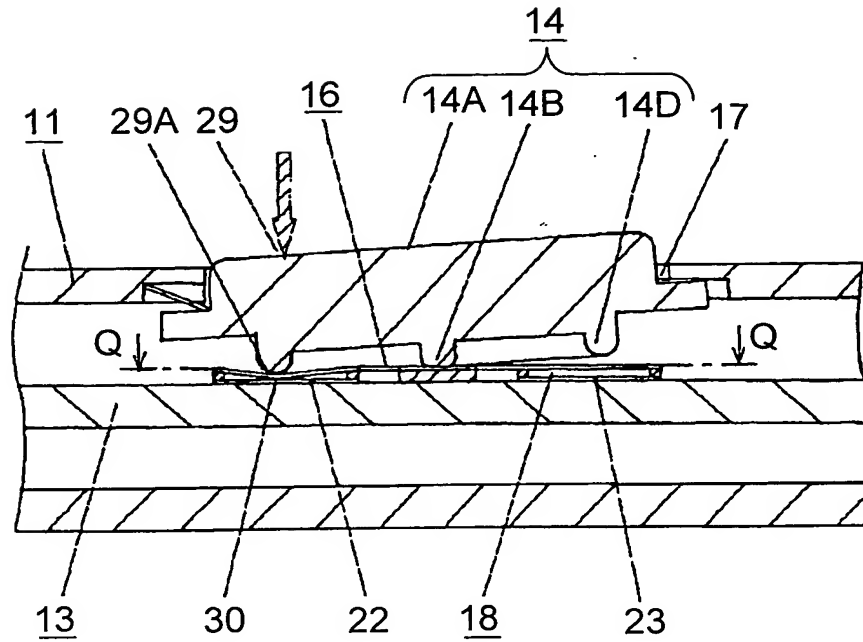
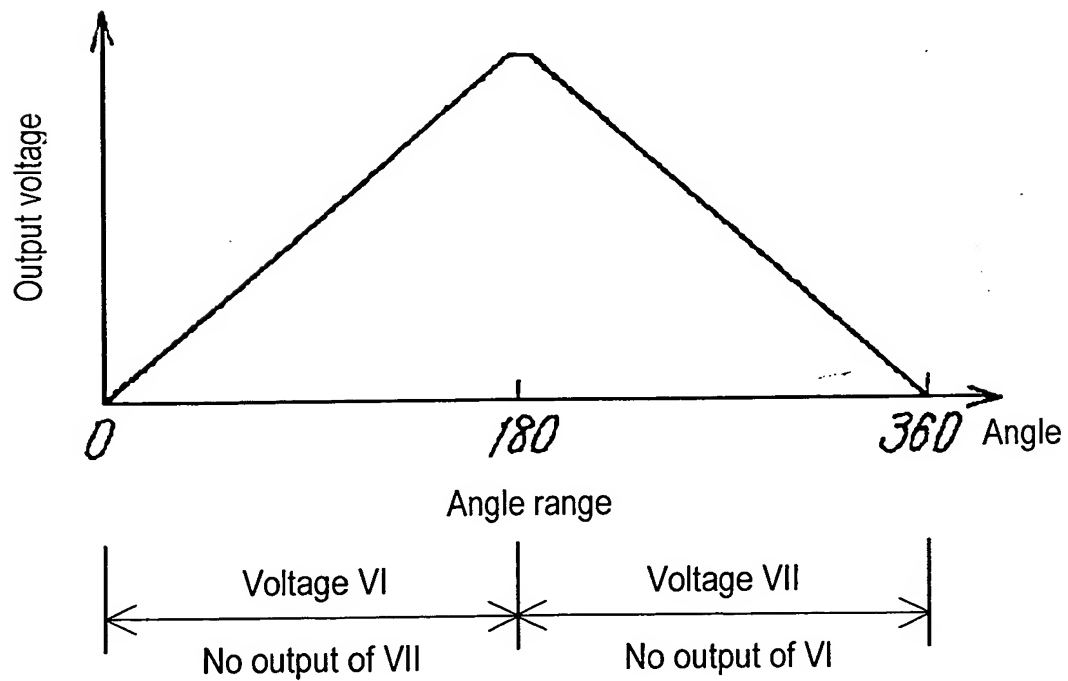
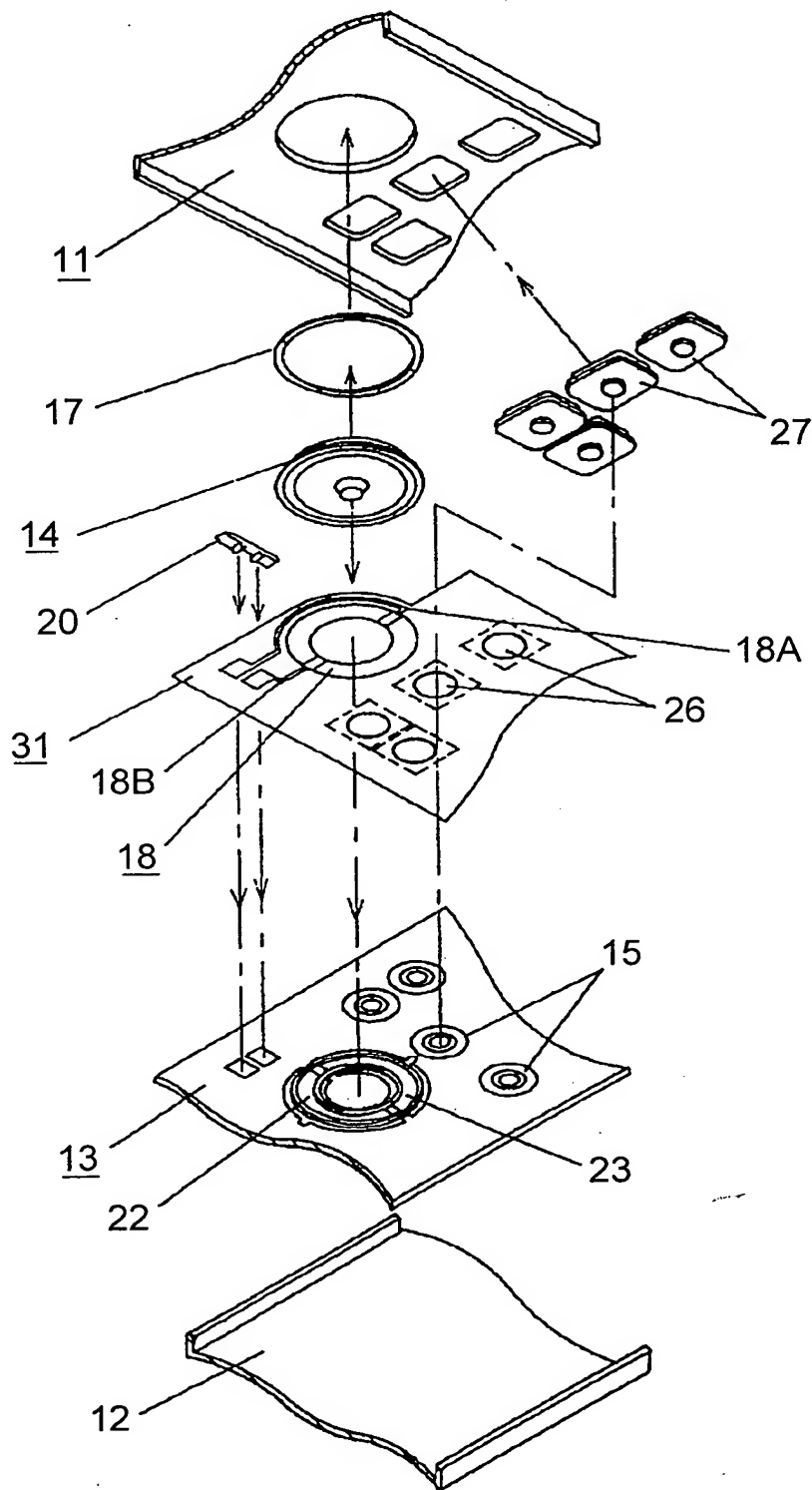


FIG. 6



5/33

FIG. 7



6/33

FIG. 8

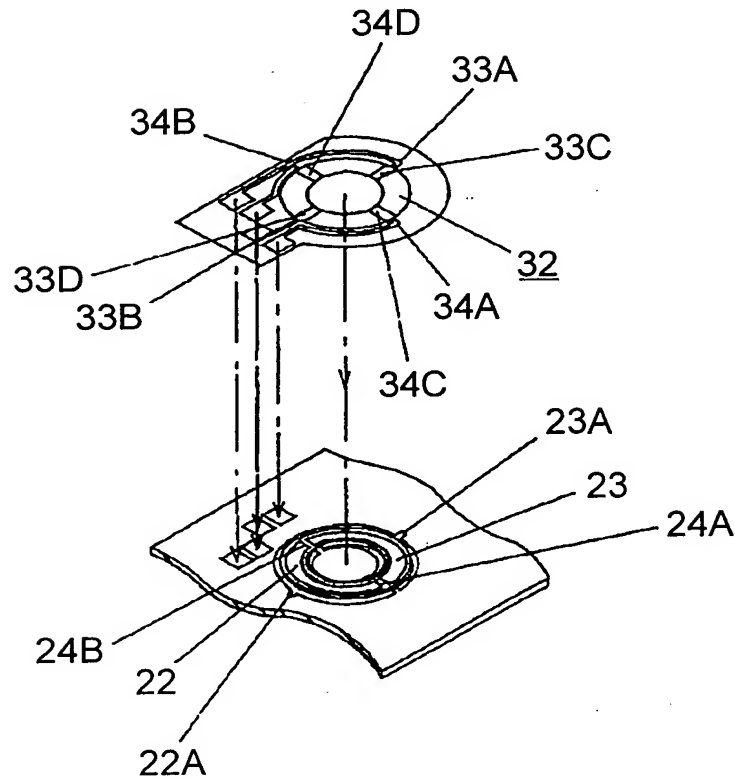
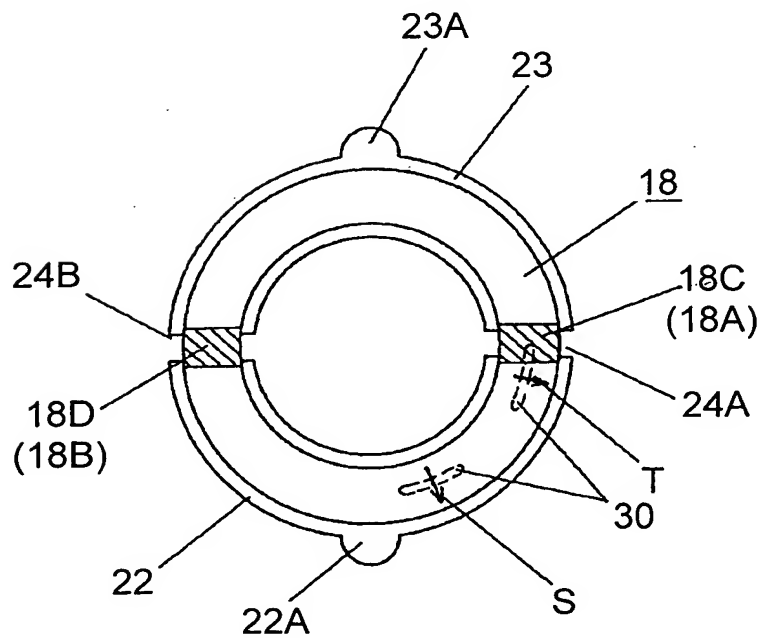


FIG. 9



7/33

FIG. 10

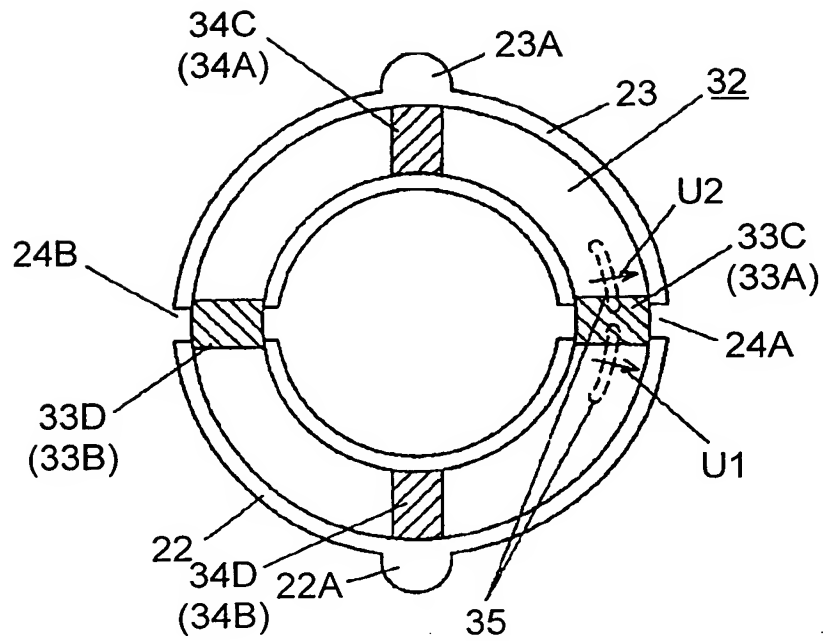


FIG. 11

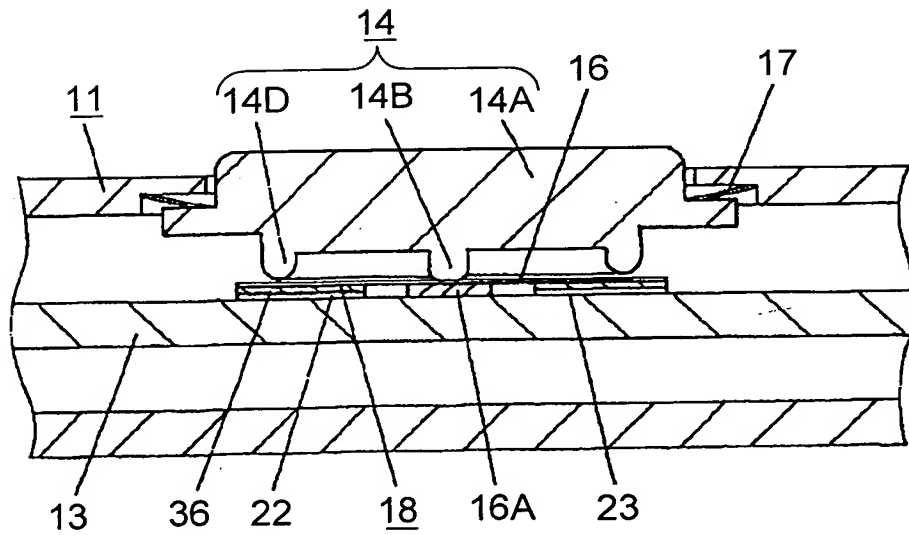
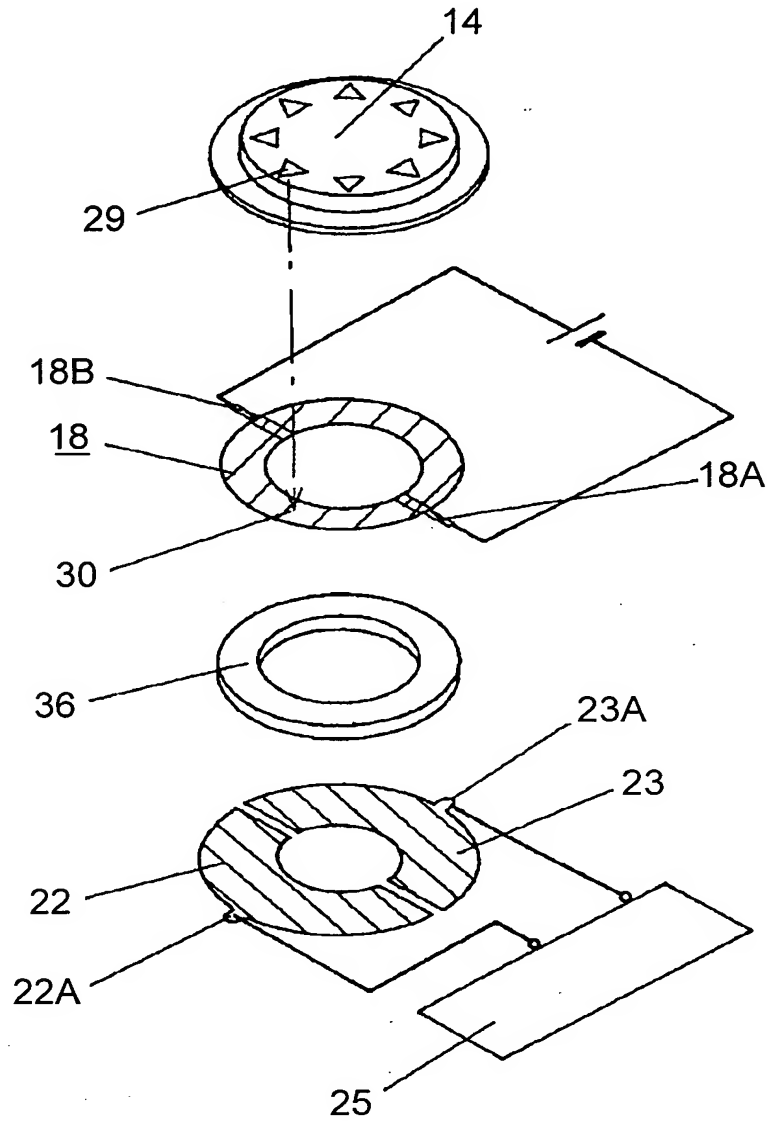


FIG. 12



9/33

FIG. 13

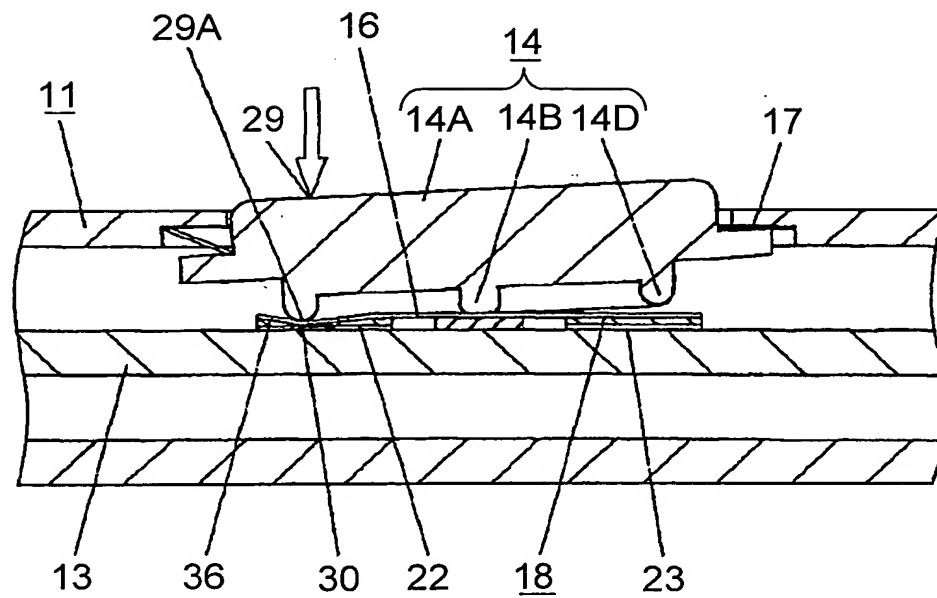
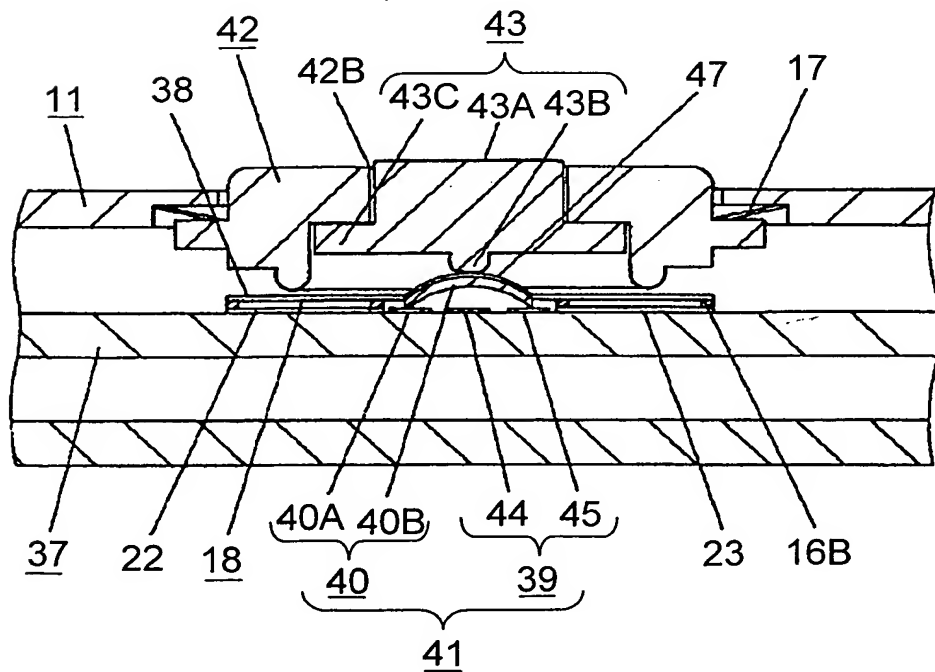
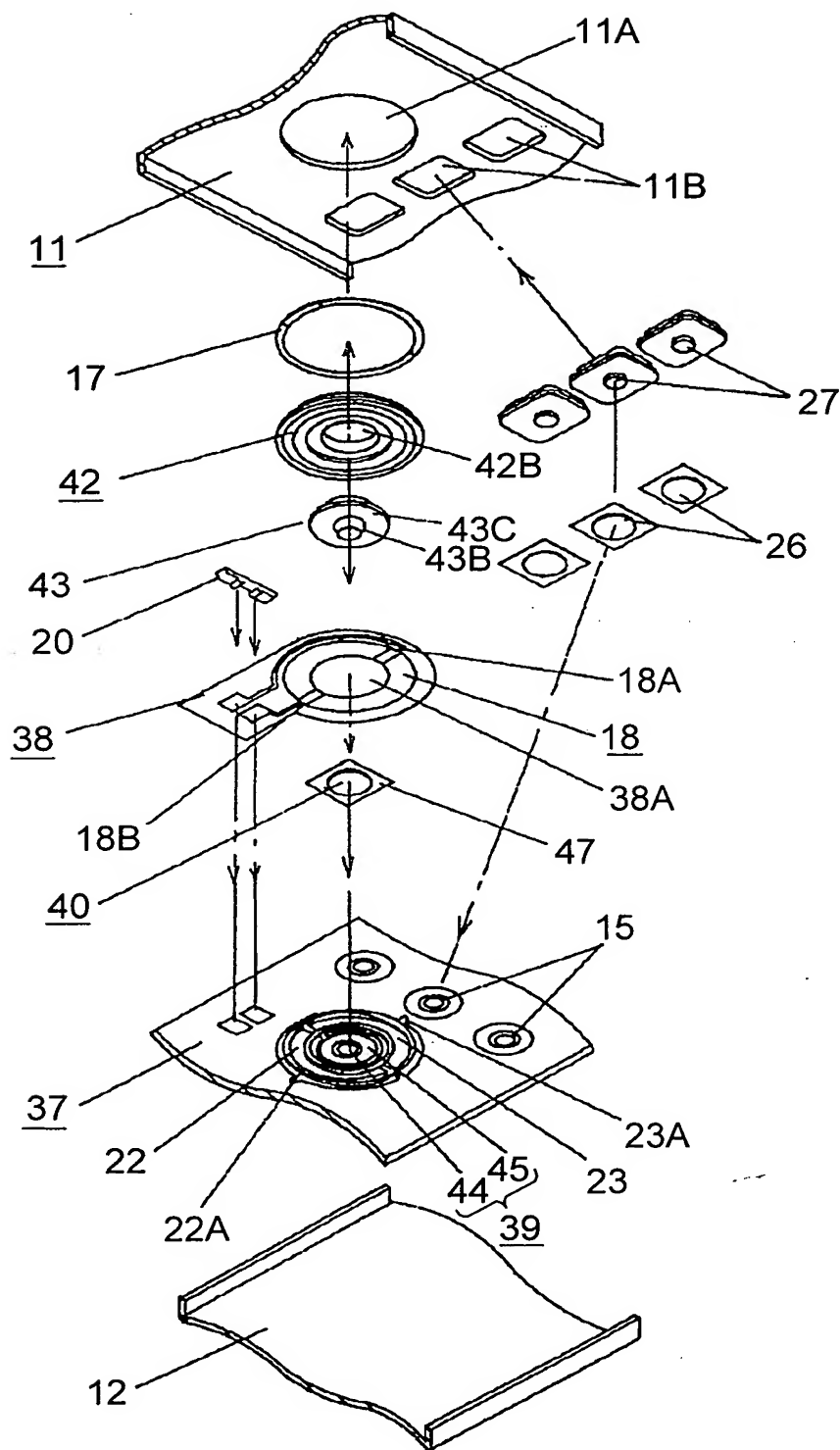


FIG. 14



10/33

FIG. 15



11/33

FIG. 16

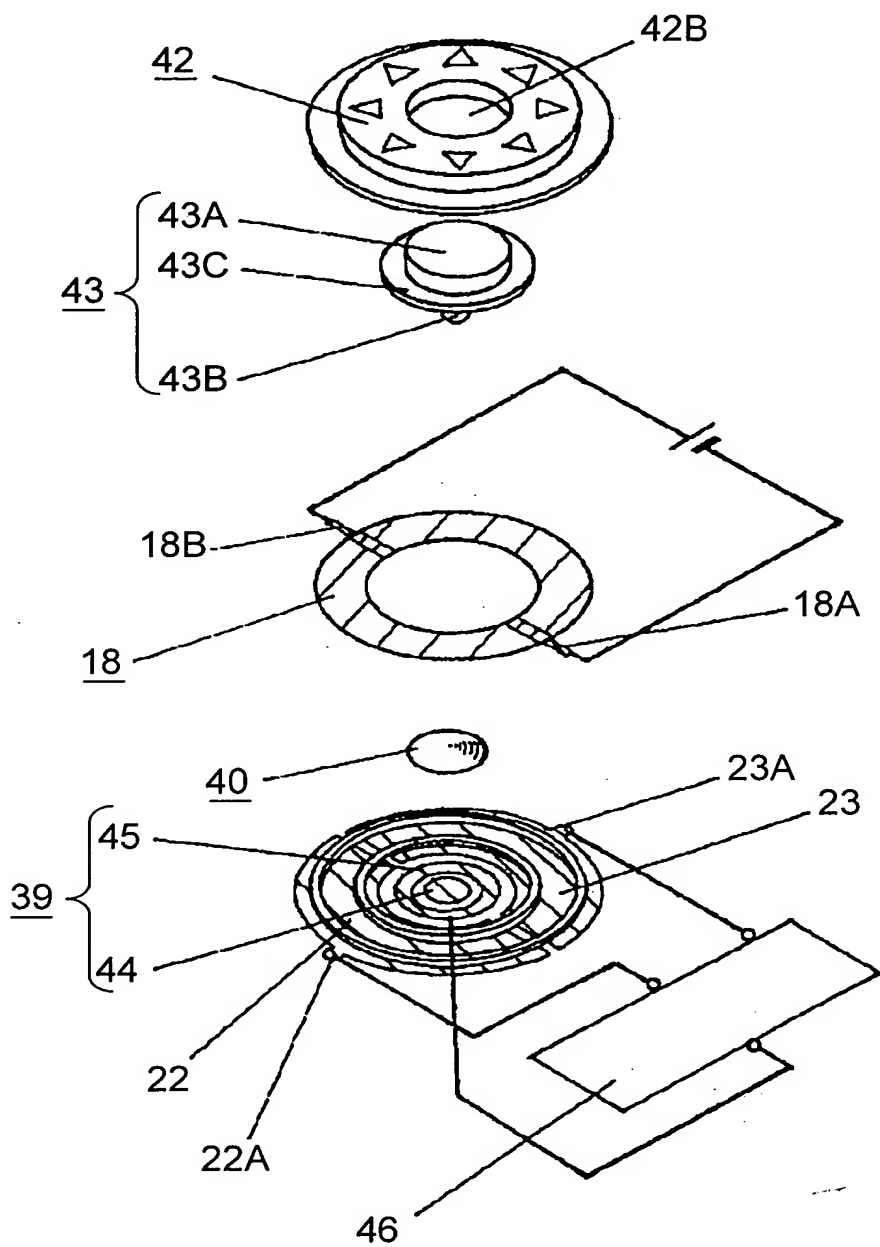


FIG. 17

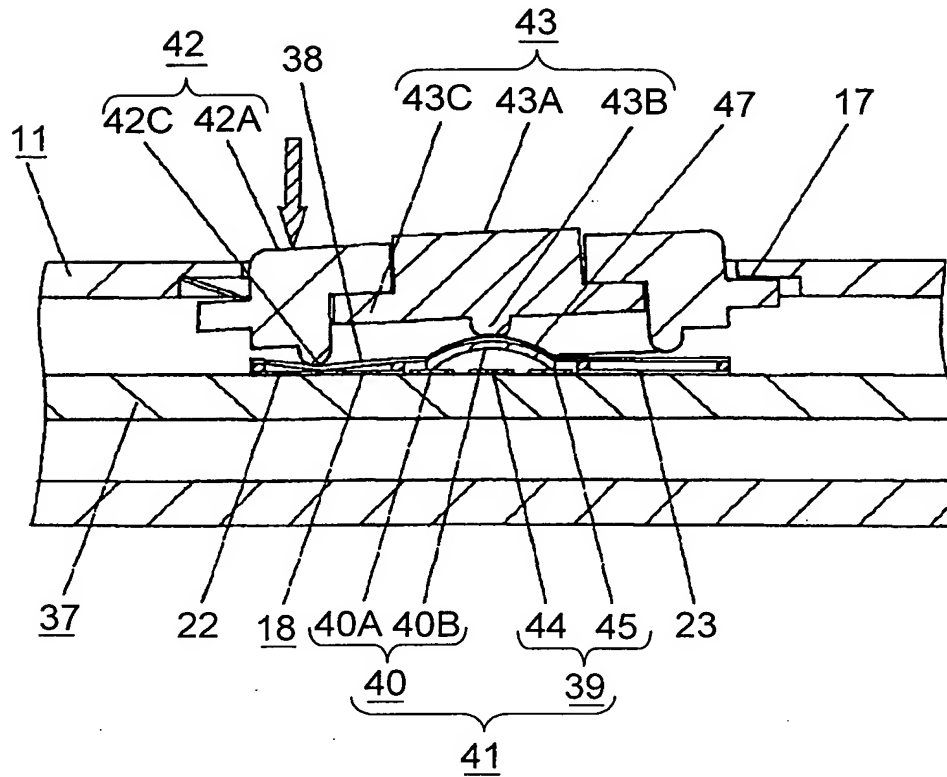


FIG. 18

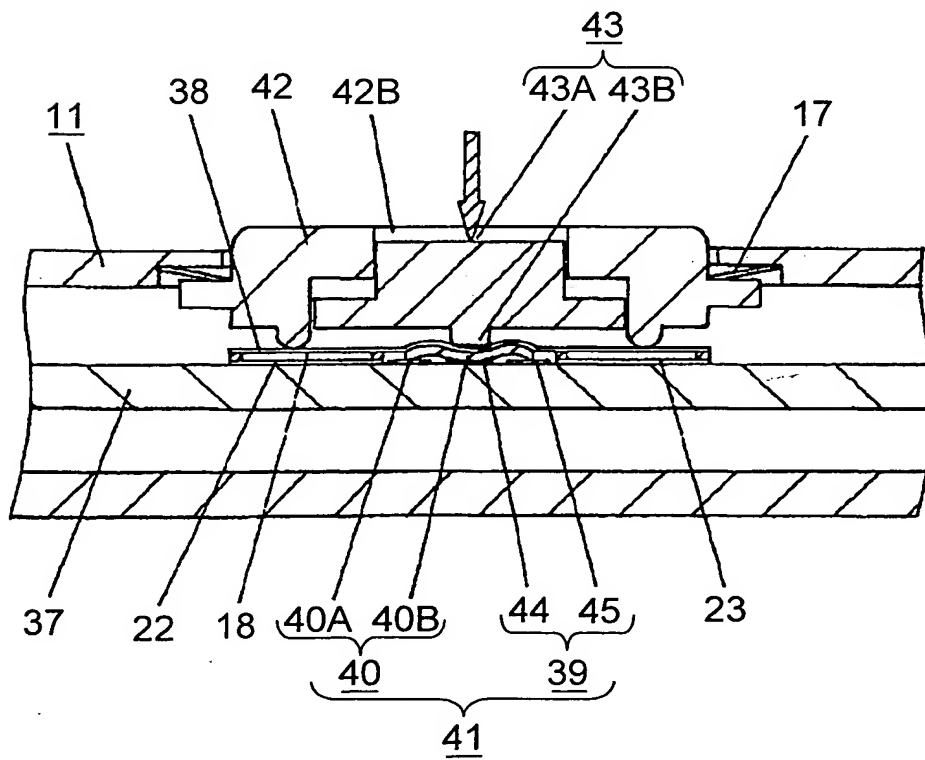


FIG. 19

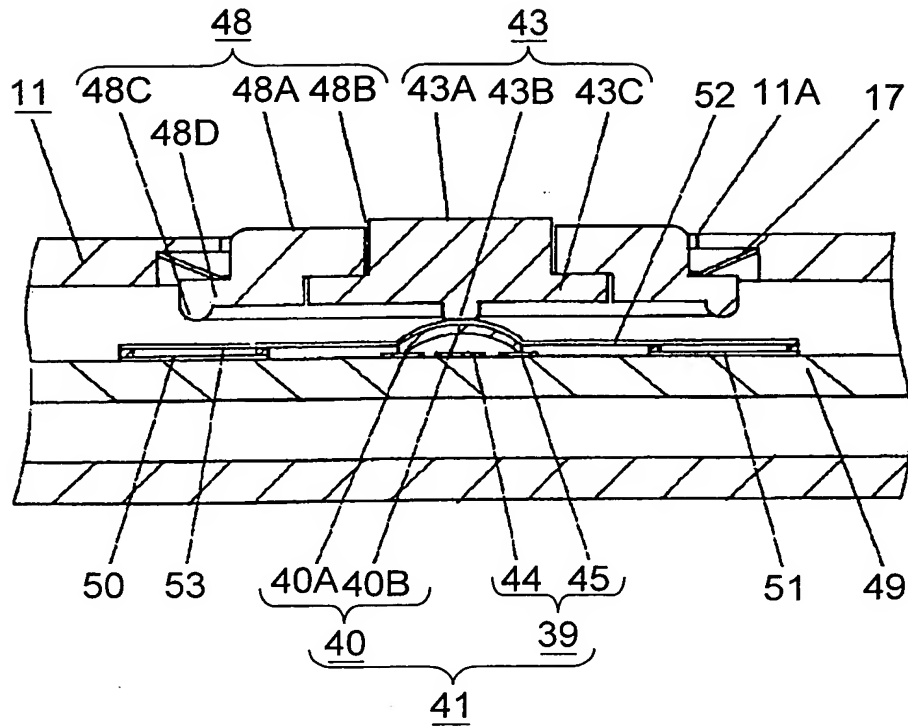


FIG. 20

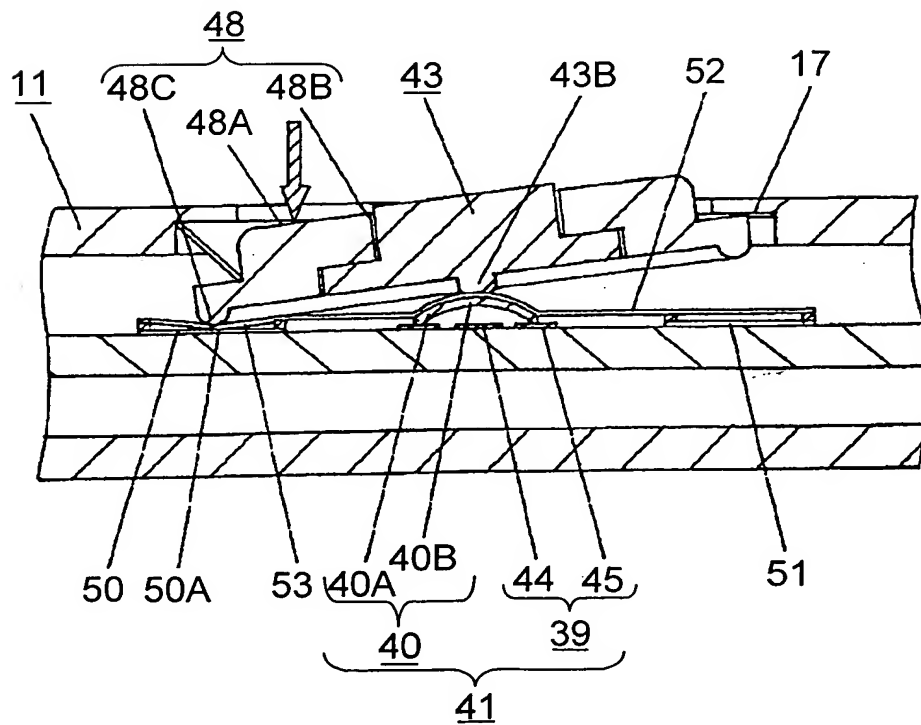


FIG. 21

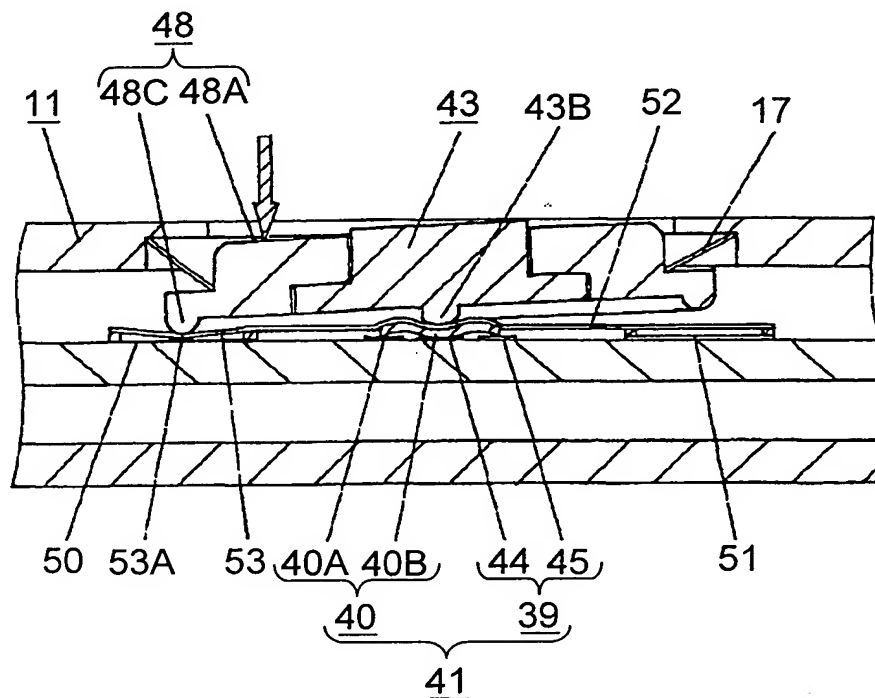


FIG. 22

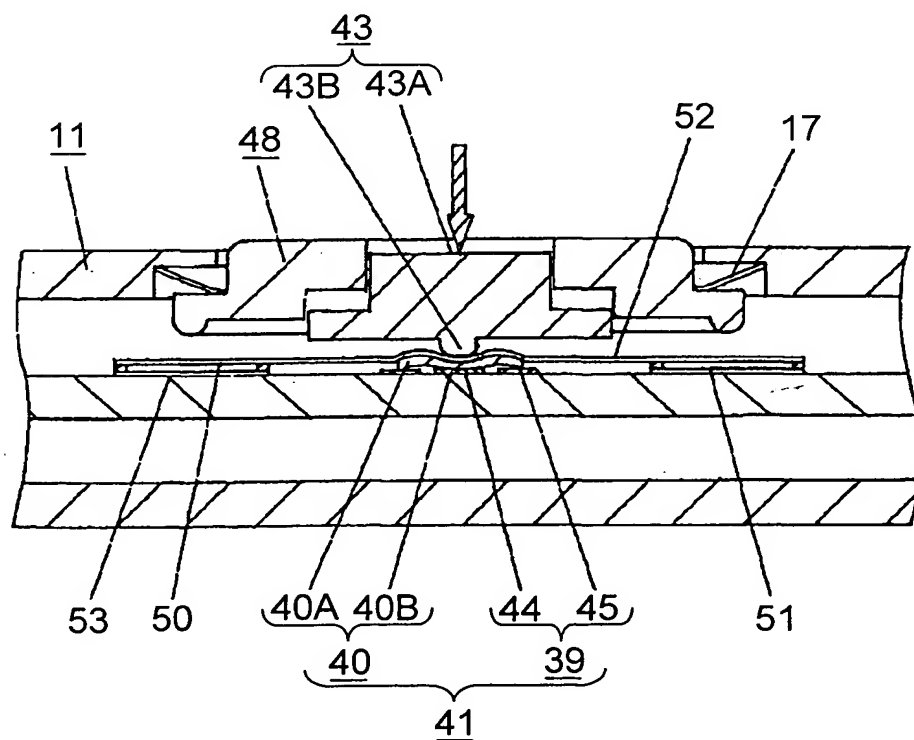


FIG. 23

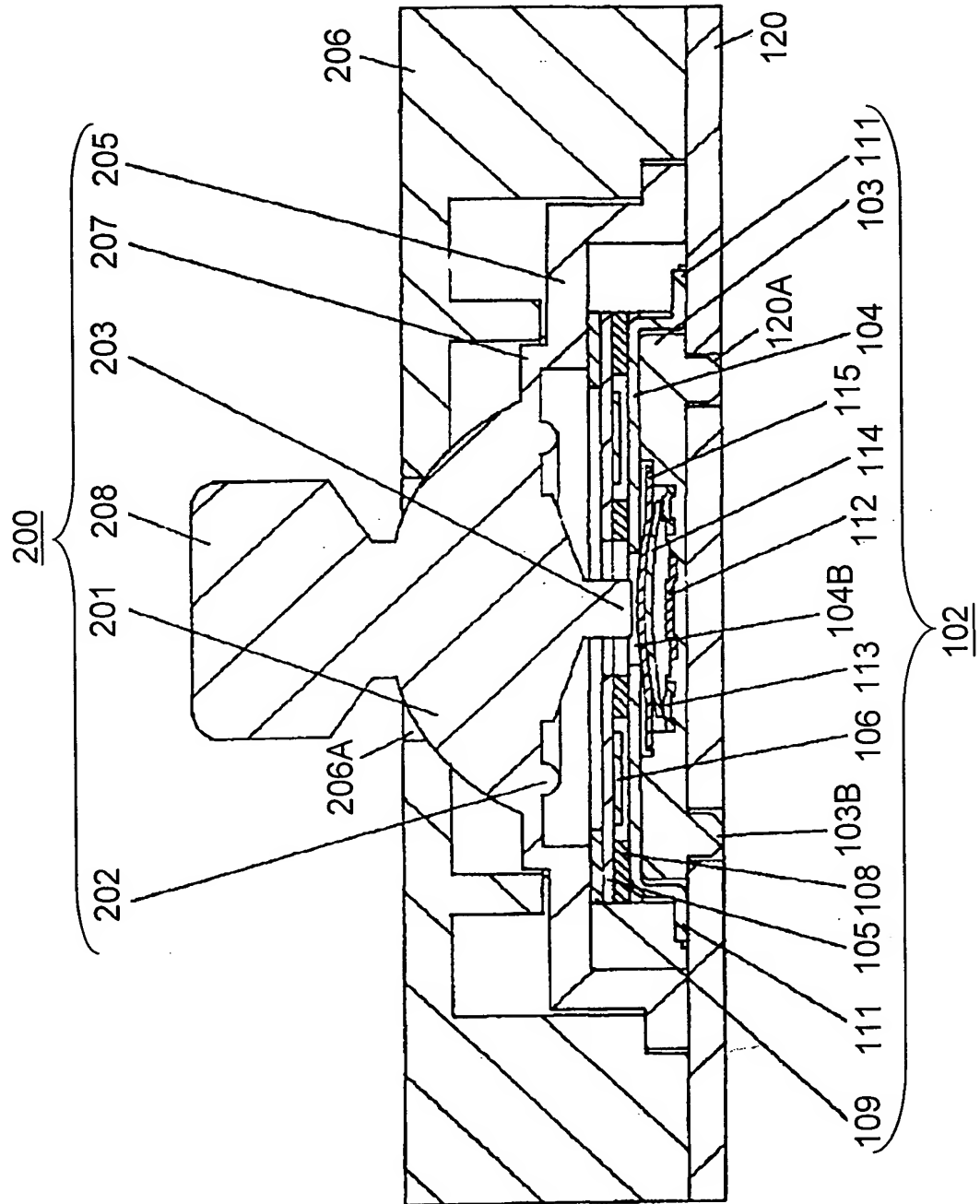
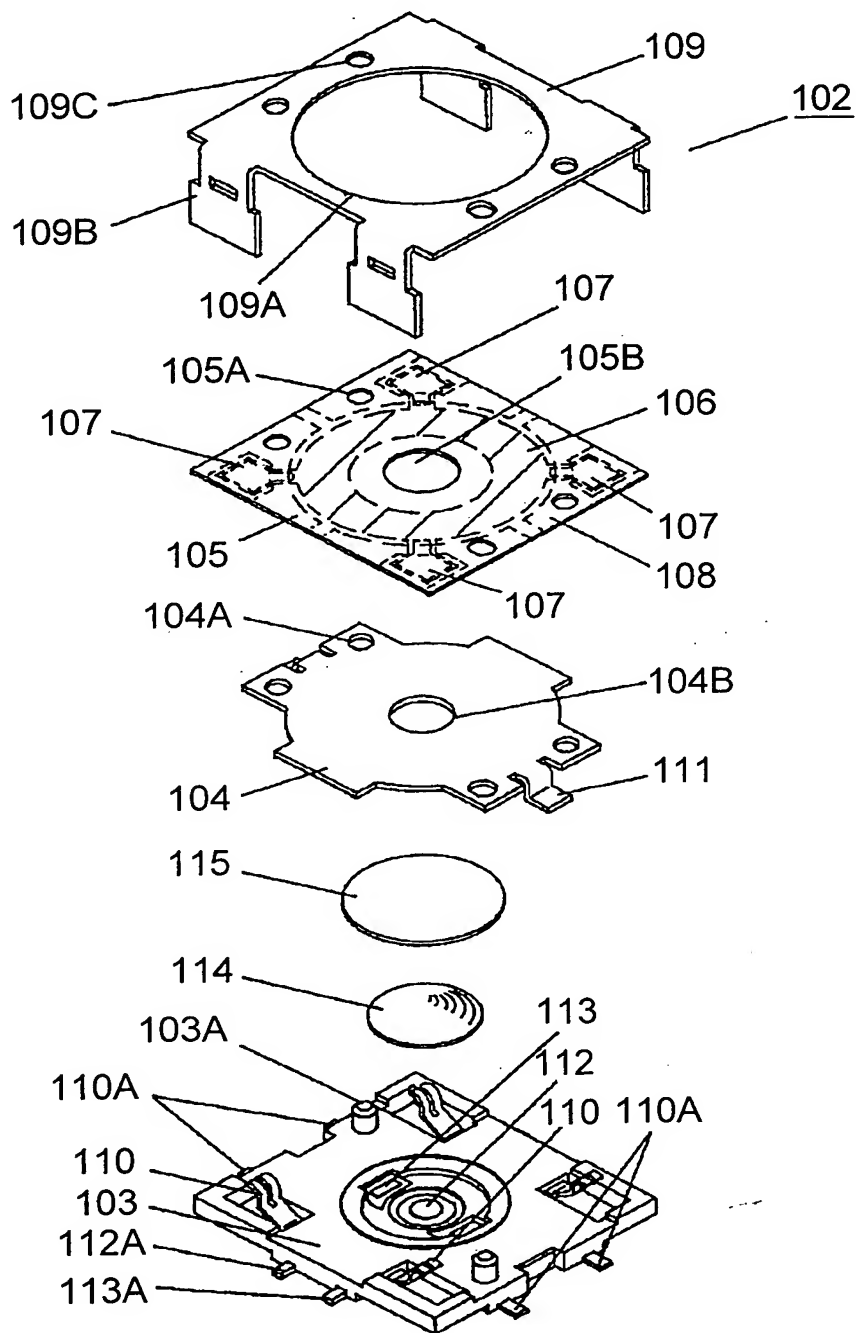


FIG. 24



17/33

FIG. 25

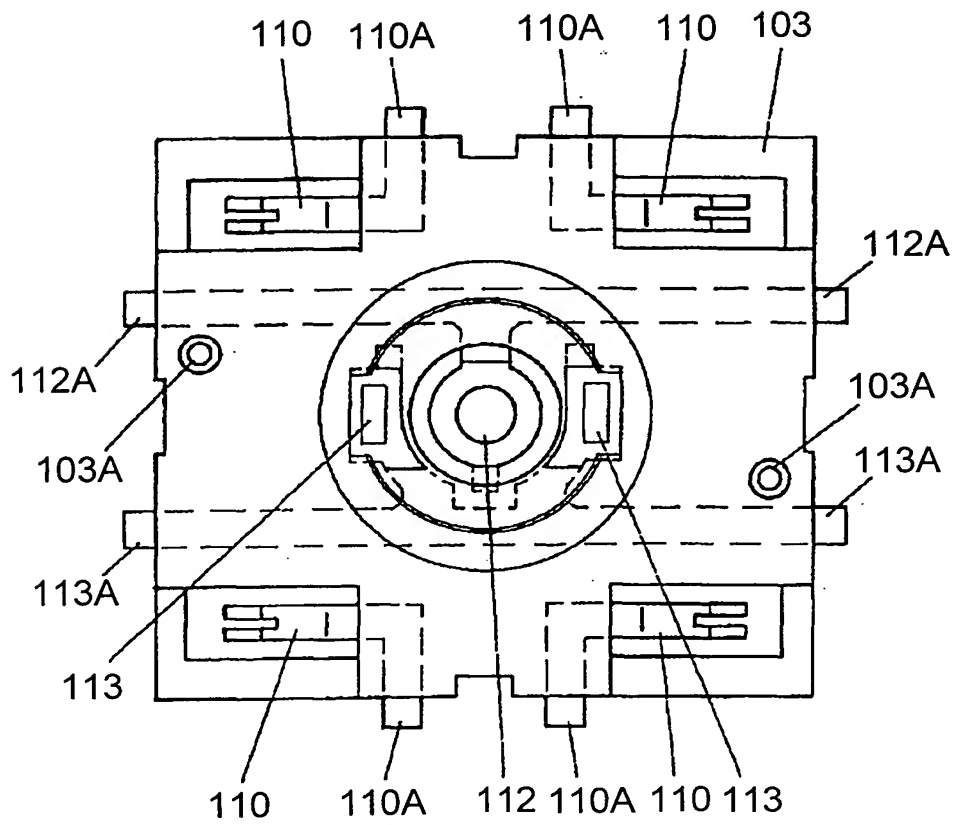
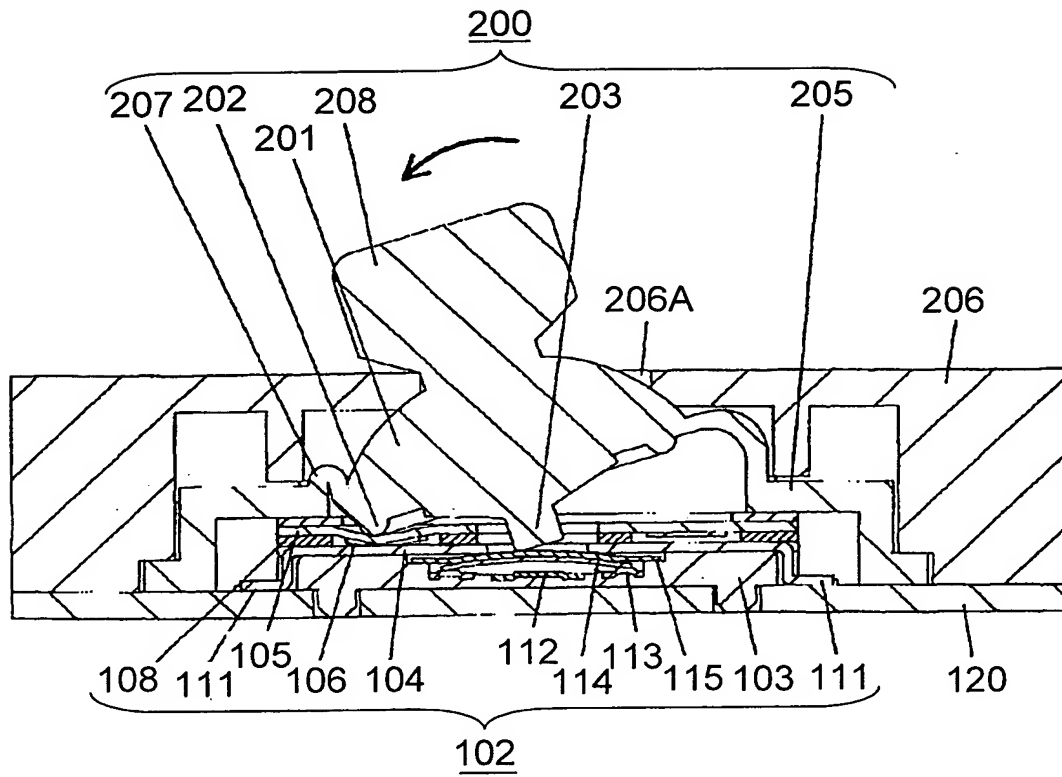


FIG. 26



19/33

FIG. 27

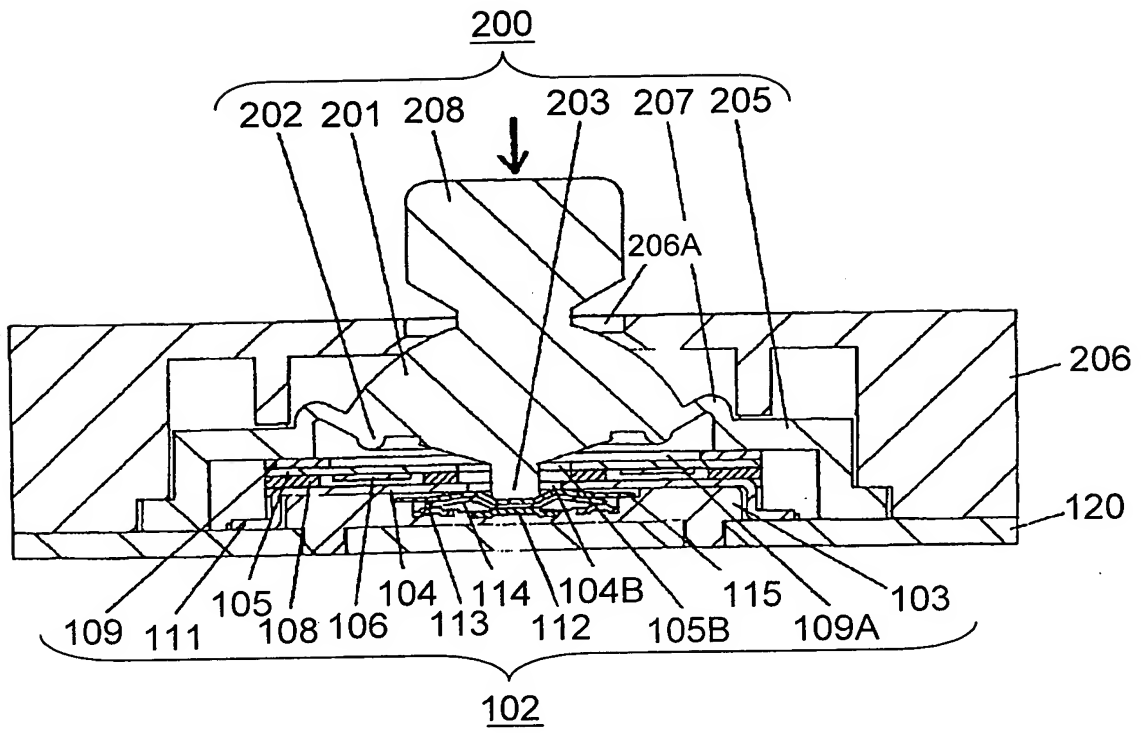


FIG. 28

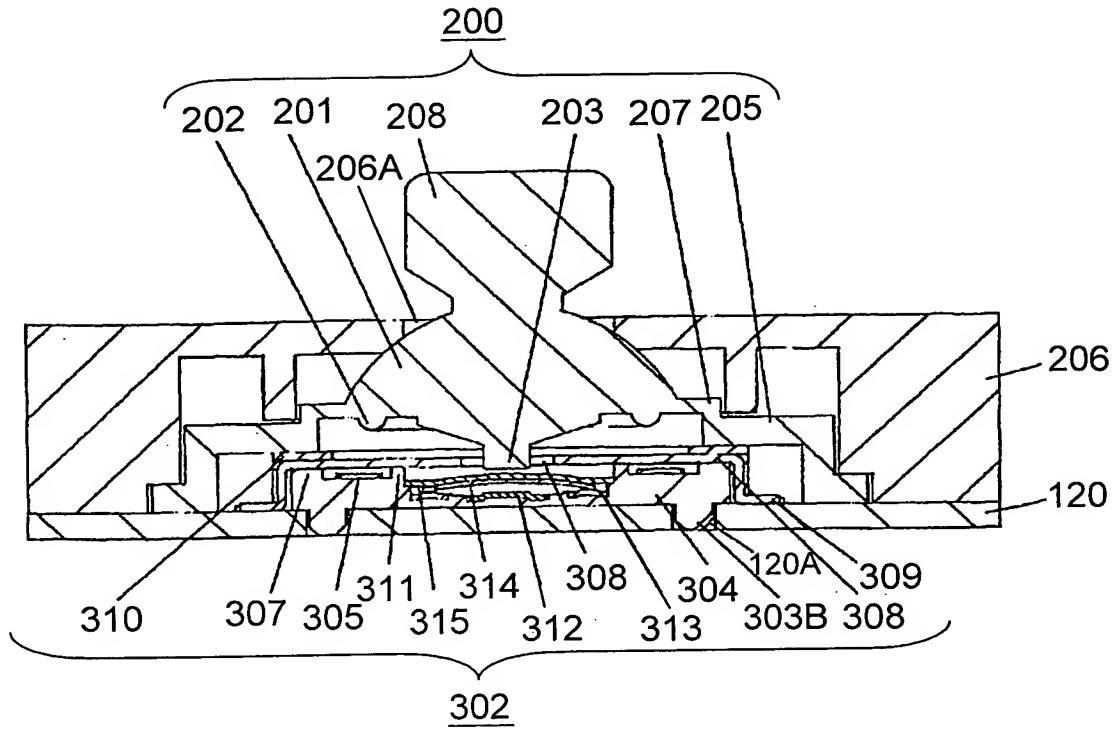


FIG. 29

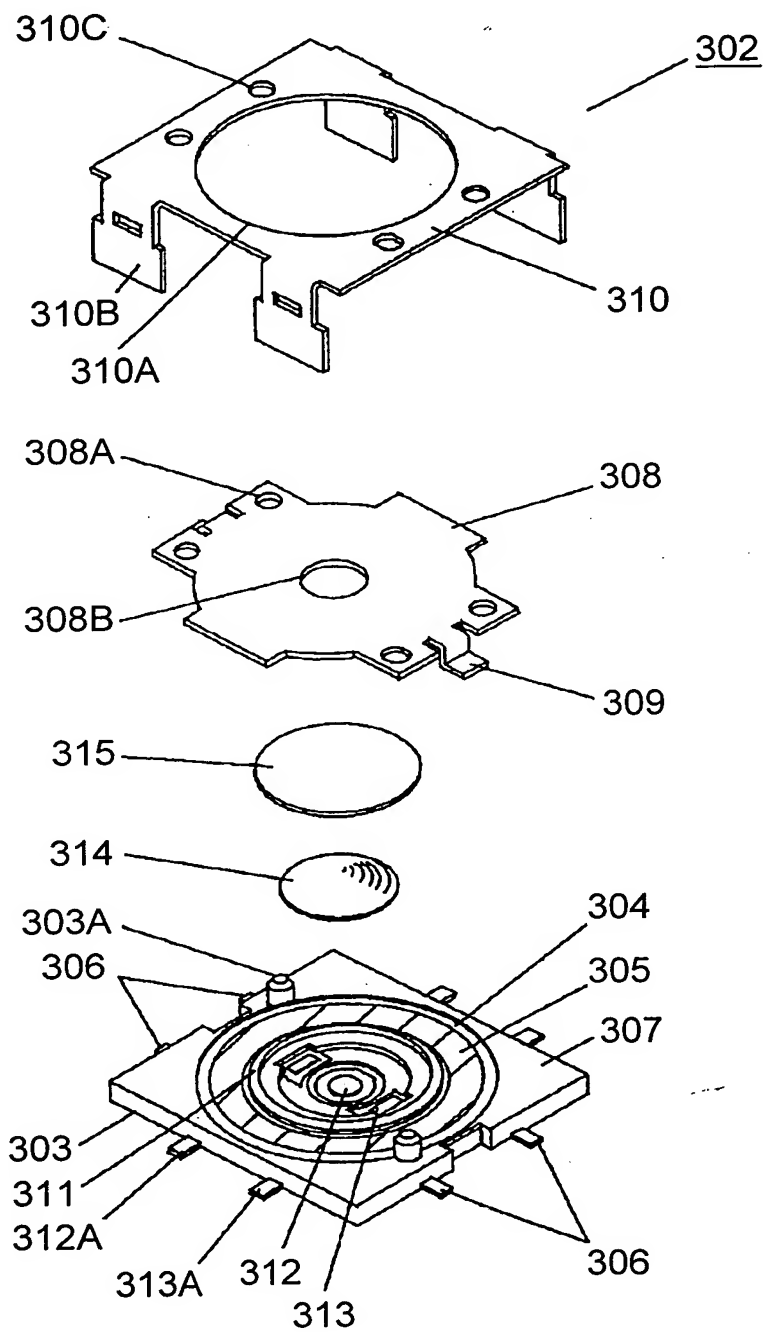


FIG. 30

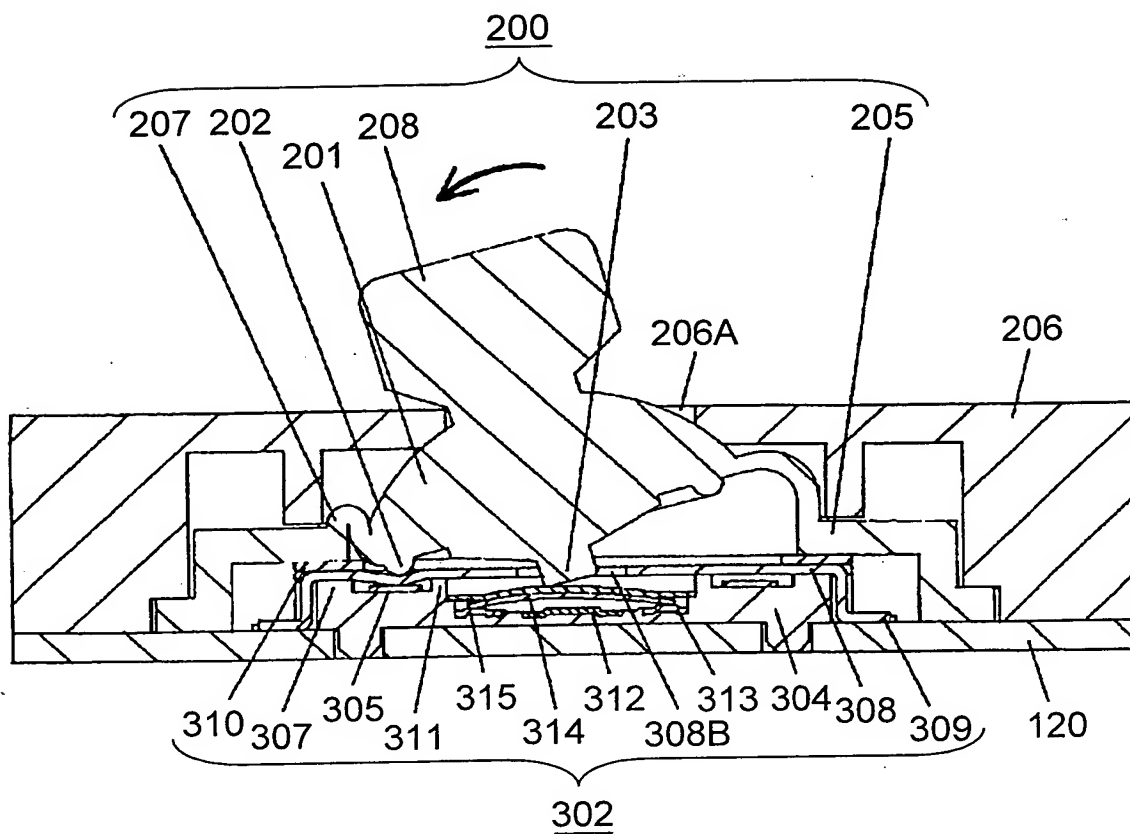


FIG. 31

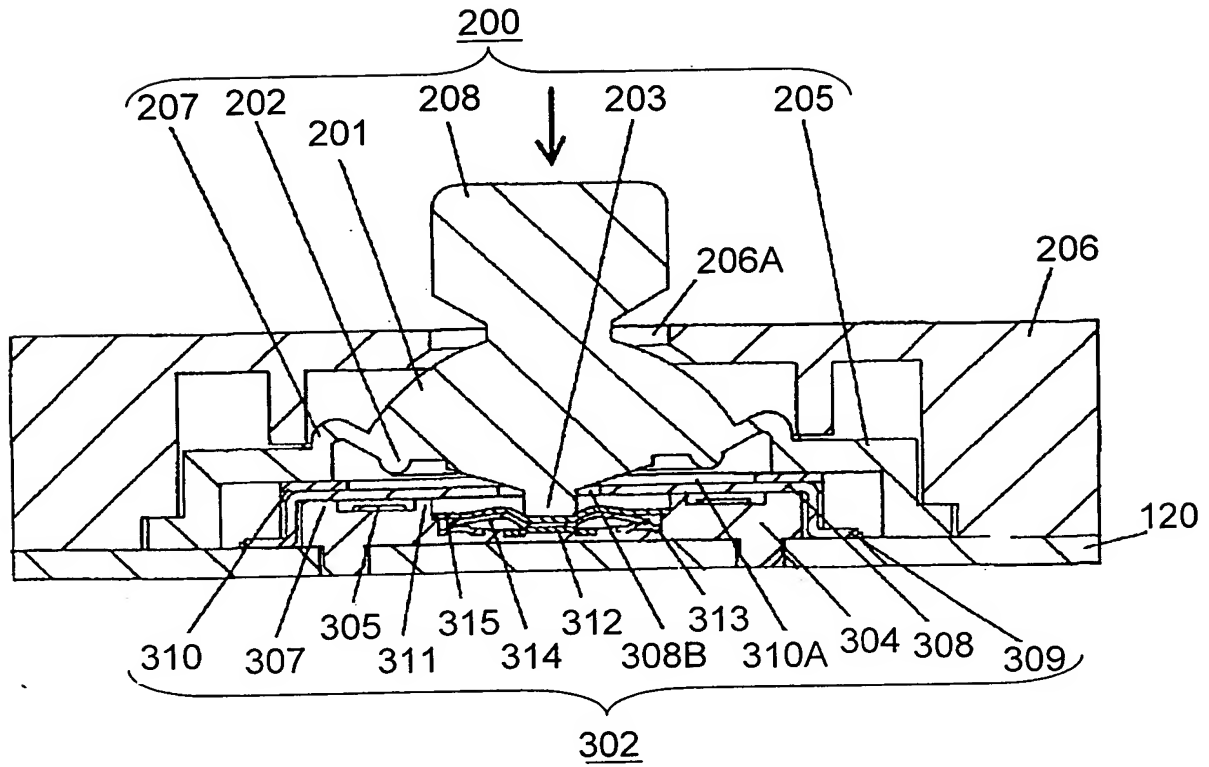
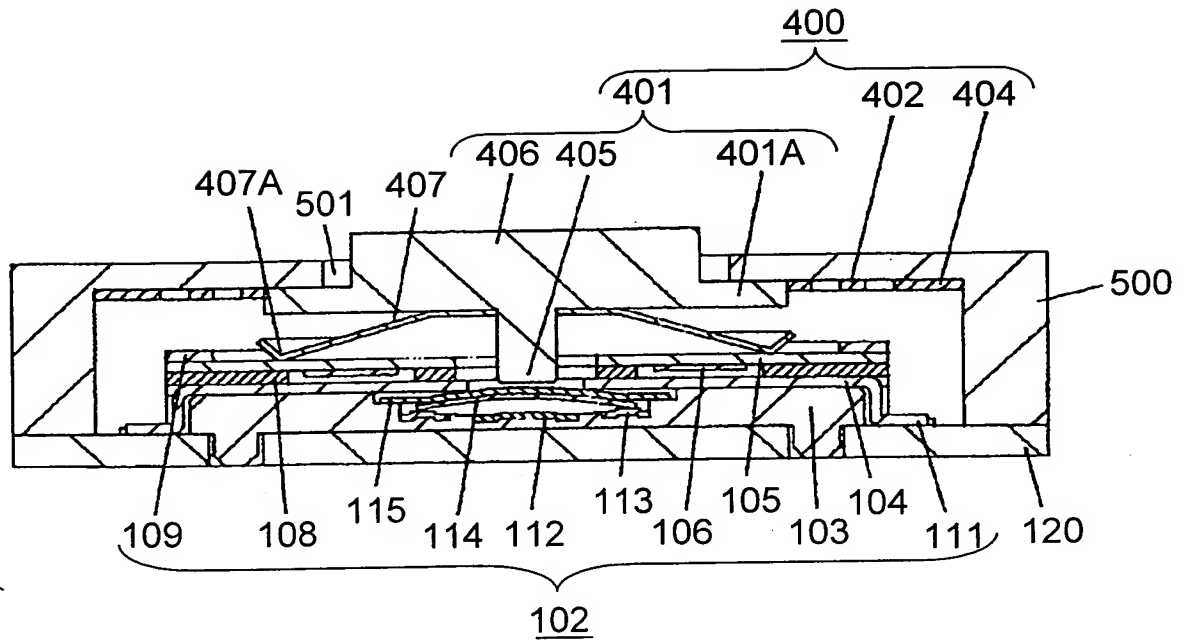
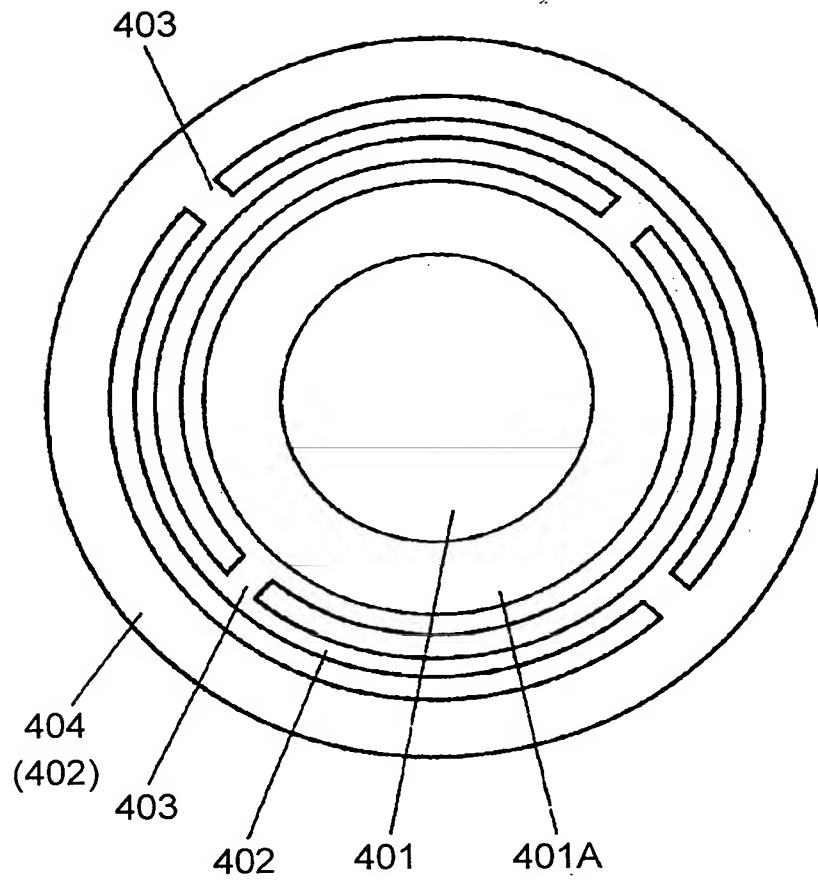


FIG. 32



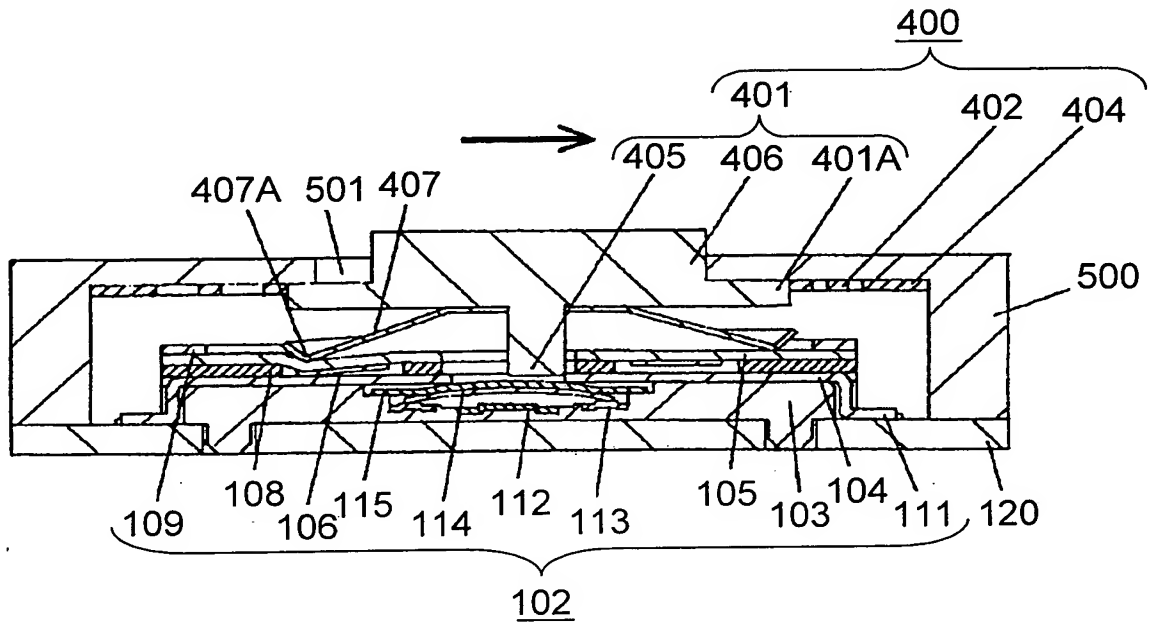
25/33

FIG. 33



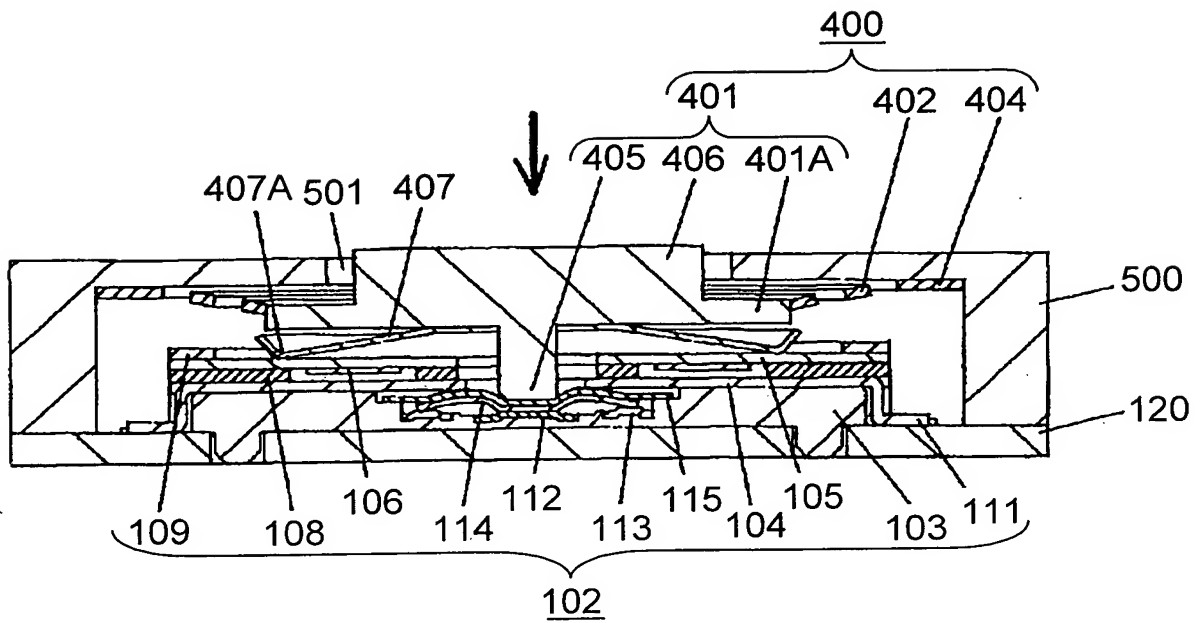
26/33

FIG. 34



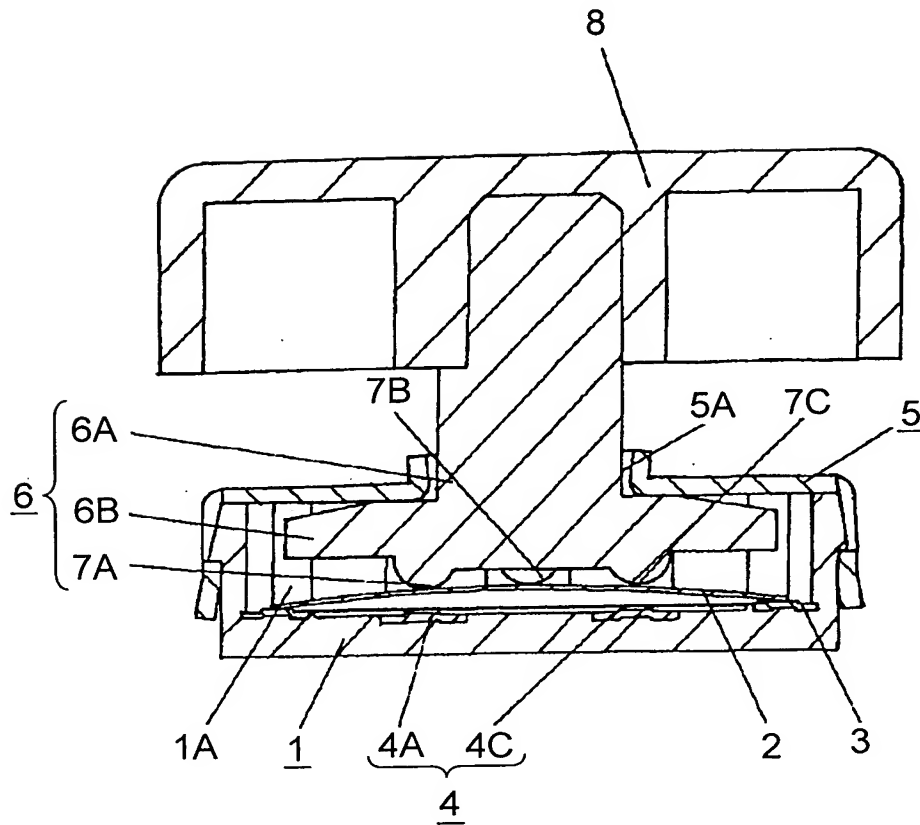
27/33

FIG. 35



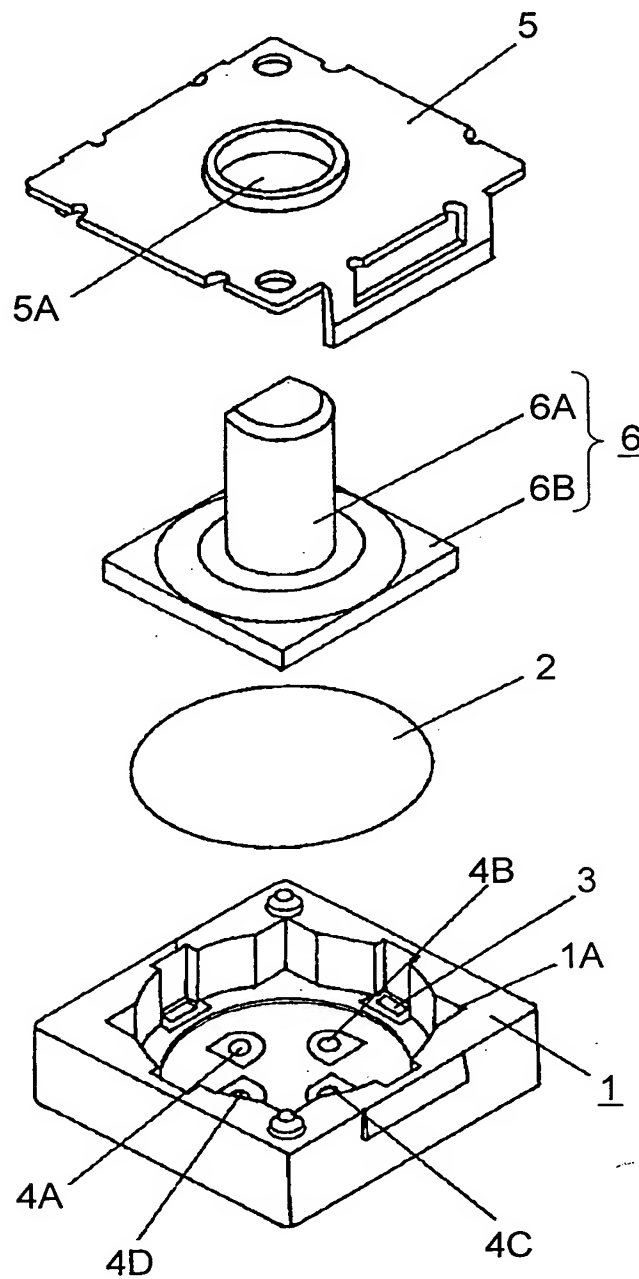
28/33

FIG. 36



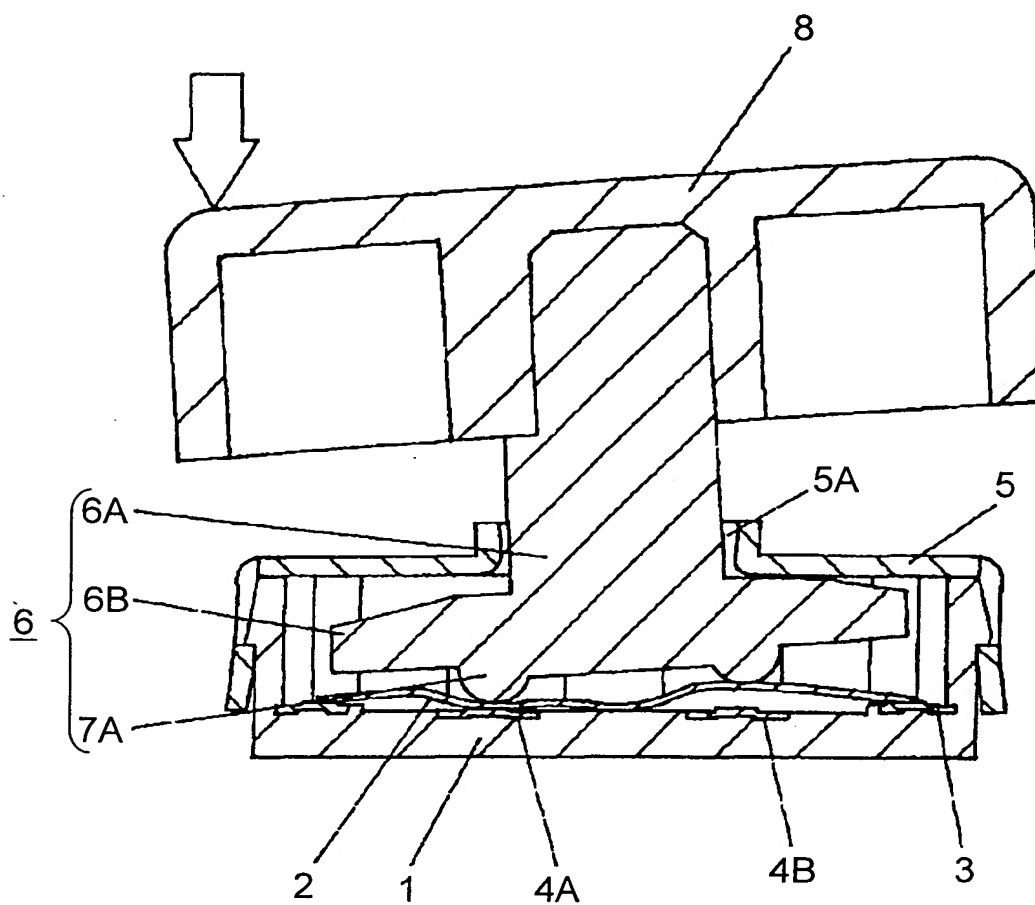
29/33

FIG. 37



30/33

FIG. 38



Reference numerals in the drawings

11	top casing
11A	through-hole
12	bottom casing
13, 37, 49, 120	printed circuit substrate
14, 42, 48	knob
14A, 42A, 43A	upper surface
14B, 43B	protrusion
14C, 43C, 48D	flange
14D, 42C, 48C	protruded section
16, 38, 52	flexible insulating substrate
16A	spacer
16B, 108	insulating spacer
17	flat spring
18, 32, 53, 106, 305	resistance element layer
18A, 18B, 22A, 23A, 33A, 33B, 34A, 34B	lead
107	terminal
18C, 18D, 33C, 33D, 34C, 34D	electrode
19A, 19B	terminal
20	pressing spring
21A, 21B	connection point
22, 50	first conductive layer
23, 51	second conductive layer
24A, 24B	insulating section
25, 46	microprocessor
29	point to be pressed
29A	point
30, 35, 53A	contact point
31	flexible printed circuit substrate
36	conductive plate
38A	hole
39	fixed contact
40, 114, 314	moving contact
40A	lower rim section
40B	central convex section
41	switch contact

42B, 48B	through-hole
43	push switch
44, 112, 312	central contact
45, 113, 313	outer contact
47, 115, 315	adhesive tape
48A	section to be pressed
102, 302	electronic component
103, 303	casing
103A, 303A	positioning protrusion
103B, 303B	boss
104, 308	plane substrate
104A, 105A, 109C, 308A, 310C	positioning hole
104B, 105B, 308B	aperture for pressing
105, 304	insulating substrate
109, 310	metal cover
109A, 206A, 310A, 501	aperture for operation
109B, 310B	fixing leg
110	resilient leg
110A, 306	input terminal
111, 309	output terminal
112A, 113A, 312A, 313A	switch terminal
120A	through-hole
200, 400	operating section
201	hemisphere section
202	ring-shaped protrusion
203, 405	central convex section
206, 500	covering-material
207	resilient section
208	control knob
307	plane circumference section
311	internal section
401	circular controlling section
401A	brim
402	ring-shaped section
403	bridge
404	outermost ring-shaped section

33/33

406

upper section

407

resilient member

407A

tip